Title (en)

VERTICALLY CONTACTED ELECTRONIC COMPONENT AND METHOD FOR PRODUCING SAME

Title (de)

VERTIKAL KONTAKTIERTES ELEKTRONISCHES BAUELEMENT SOWIE VERFAHREN ZUR HERSTELLUNG EINES SOLCHEN

Title (fr)

COMPOSANT ÉLECTRONIQUE À CONTACT VERTICAL AINSI QUE PROCÉDÉ DE FABRICATION ASSOCIÉ

Publication

EP 2409327 A1 20120125 (DE)

Application

EP 10712326 A 20100322

Priority

- EP 2010001792 W 20100322
- DE 102009014237 A 20090320

Abstract (en)

[origin: WO2010105853A1] The invention relates to an electronic component, having at least one contact surface, which is located in a contact plane, at least one insulating layer, which is above the contact plane, at least one stabilizing layer, disposed on the insulating layer, for increasing a mechanical stability of the component and at least one bonding and/or soldering contact, wherein the insulating layer and the stabilizing layer have at least one opening, which opens towards one surface of the stabilizing layer, which faces away from the contact surface, and which extends through the stabilizing layer and the insulating layer to the contact surface, and wherein the bonding and/or soldering contact extends across the stabilizing layer and touches the contact surface through the opening.

IPC 8 full level

H01L 23/31 (2006.01); **H01L 23/00** (2006.01)

CPC (source: EP US)

H01L 23/3114 (2013.01 - EP US); **H01L 23/3171** (2013.01 - EP US); **H01L 23/3192** (2013.01 - EP US); **H01L 24/04** (2013.01 - EP US); H01L 23/562 (2013.01 - EP US); H01L 2224/05599 (2013.01 - EP US); H01L 2224/85399 (2013.01 - EP US); H01L 2924/00014 (2013.01 - EP US); H01L 2924/01005 (2013.01 - EP US); H01L 2924/01006 (2013.01 - EP US); H01L 2924/01013 (2013.01 - EP US); H01L 2924/01014 (2013.01 - EP US); H01L 2924/0102 (2013.01 - EP US); H01L 2924/01022 (2013.01 - EP US); H01L 2924/01023 (2013.01 - EP US); H01L 2924/01033 (2013.01 - EP US); H01L 2924/01068 (2013.01 - EP US); H01L 2924/01072 (2013.01 - EP US); H01L 2924/01074 (2013.01 - EP US); H01L 2924/014 (2013.01 - EP US); H01L 2924/05042 (2013.01 - EP US); H01L 2924/12032 (2013.01 - EP US)

Citation (search report)

See references of WO 2010105853A1

Citation (examination)

US 2005082685 A1 20050421 - BOJKOV CHRISTO P [US], et al

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO SE SI SK SM TR

DOCDB simple family (publication)

WO 2010105853 A1 20100923; EP 2409327 A1 20120125; JP 2012521082 A 20120910; JP 5732035 B2 20150610; US 2012038058 A1 20120216

DOCDB simple family (application)

EP 2010001792 W 20100322; EP 10712326 A 20100322; JP 2012500155 A 20100322; US 201013257029 A 20100322